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NorCLAD Hole Prep & Metallization Guidelines

These guidelines were developed to provide fabricators with basic information on processing PTH and double sided circuit processing. For more detailed information please contact Polyflon directly.

Hole Preparation:

1. Remove any debris from holes. Holes must be free of smear.
2. Mechanically scrub panel with reduced pressure. Excessive pressure may cause distortion. Dry scrubbed panel with compressed air to remove water from holes.
3. Immersion in a bath of 75% Denatured Alcohol / 25% Methylene Chloride for 3-5 minutes. Panels must be constantly agitated.
4. Use compressed air to drive out solution from holes.
5. Oven dry at 165F for 10 minutes and move immediately to next step.
6. Immerse in adhesion promoter/conditioner for 30 seconds with continuous agitation. Rinse Well. Adhesion promoters are available from:

MacDermid	MacDermid
Metex 9420	Metex 20

Electroless Procedure

1. Predip: 30 seconds to 1 min in Sodium Chloride Crystal Solution at 75-80F
2. Catalyst: 5 min at 75-80F. Rinse Well.
3. Accelerator: 15% Floboric Acid for 5 mins at 75-80F
4. Deposit thin film of Electroless Copper (~80F).
5. Flash electrolytic plate for 10min at ASF. Dry and inspect for board for voiding.
6. If voided, repeat Hole Preparation and Electroless Procedure.